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Reg No.:

Name:

APJ ABDUL KALAM TECHNOLOGICAL UNIVERSITY SIXTH SEMESTER B.TECH DEGREE EXAMINATION(R&S); MAY 2019

Course Code: EC304

Course Name: VLSI

Max. Marks: 100

Duration: 3 Hours

Pages: 2

PART A Answer any two full questions, each carries 15 marks

Marks

(5)

- 1 a) How electronic grade silicon is prepared from raw SiO₂?
 - b) Illustrate the dry and wet oxidation technique used in IC fabrication with (10) schematic diagram.
- 2 a) With the help of mathematical equations, explain the distribution of impurities in a (10) semiconductor in ion implantation process.
 - b) Phosphorous is implanted in a p-type silicon sample with a uniform doping (5) concentration of 5×10^{16} atoms per cm³. If the beam current density is 2.5μ A per cm² and the implantation time is 8 minutes, calculate the implantation dose and peak impurity concentration. Assume $\Delta Rp=0.3\mu m$
- 3 a) Explain N-well CMOS IC fabrication sequence with the help of neat diagrams. (10)
 - b) Explain one method of fabrication of capacitor structure in integrated circuits. (5)

PART B

Answer any two full questions, each carries 15 marks

- 4 a) Explain the various types of power dissipation in CMOS inverter? Derive the (10) expression for total power consumption of a CMOS inverter.
- b) Why PMOS transistor can pass only strong ones and NMOS can pass strong zeros. (5)
- 5 a) Draw the circuit diagram and layout of a two input CMOS NAND gate. (10)
 - b) Implement the function u = A'B+AB' and v = AB+A'B' using complementary (5) pass transistor logic.
- 6 a) Explain the structure and working of a transmission gate. (10) Implement 4×1 multiplexer using transmission gates.
 - b) Implement the function f = [AB + C (DE+F)]' using static CMOS logic.⁴ (5)

PART C

Answer any two full questions, each carries 20 marks

- 7 a) Explain the read and write operation of a six transistor CMOS SRAM cell. (10)
 - b) What is FPGA? Explain its constructional details with diagram. What are the (10) advantages of FPGA?
- 8 a) Design a 4-bit × 4-bit NOR-based ROM array and explain its working. (10)
 - b) Explain the read and write operation of a three-transistor DRAM cell. (10)
- 9 a) Explain the working a 16-bit carry-by pass adder and write down the expression (10)

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for worst-case delay.

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b) Explain 4×4 bit-array multiplier with block diagram.

(10)

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Write the over of **mathematical** separations, explain the distribution of i**mpurities** may of 10 semicon-actor in ion implantation process.

Phased must is implanted to a p-type siticon sample with a uniform doping (5) For established of 5×10th atoms per cm². If the beam current density is 2.5µ A per cm² and the implantation time is 8 minutes, calculate the implantation dose and pear to mity concentration. Assumer: Rp=0.5µm

Explan A-well CMOS IC fabrication sequence with the help of near diagrams.

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inverter? Derive the . (10)		4 run -Ekelisch the vestigas type
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b) Whet I + ED's quarkstore date parts on by strong price and NMOS can pass strong zeros. (5)

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4) Exclusive the structure and working of a transmission gate.
(10) Implyment F-1 multiplexer using grossmission gates.
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PARTC

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Design a 4-bit NOR-based ROM array and explain its working.		
Expl. o the read and write operation of a three-transistor DRAM cell.		